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1. An electrical assembly comprising:
traces extending toward respective off-assembly connections; and
integrated transformer structures defined along the traces to induce
compensating crosstalk signals having opposing polarity to initial
crosstalk signals associated with mutual coupling between adjacent of
the off-assembly connections.
2. The electrical assembly of claim 1, wherein one or more of the integrated
transformer structures each comprise:
an aperture in a voltage plane of the electrical assembly;
essentially parallel portions of corresponding pairs of the traces, the essentially
parallel portions passing over the aperture.
3. The electrical assembly of claim 1, wherein one or more of the integrated
transformer structures each comprise:
an aperture in a voltage plane of the electrical assembly; and
essentially parallel portions of corresponding pairs of the traces, the essentially
parallel portions coplanar with the voltage plane and traversing the
aperture therein.
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4. The electrical assembly of claim 1, further comprising:
the off-assembly connections.
5. The electrical assembly of claim 1, including a semiconductor package,
wherein the off-assembly connections include pins, solder connections, leads,
or wires; and
wherein the traces are formed on the semiconductor package.
6. The electrical assembly of claim 1, including a board or card,
wherein the off-assembly connections include pins or leads of a semiconducto
package or solder connections or wires thereto, and



wherein the traces are formed on the board or card.



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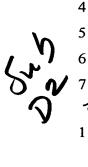
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The electrical assembly of claim 1, including a board or card,
wherein the off-assembly connections include pins, leads, solder connections
or edge connectors; and
wherein the traces are formed on the board or card.

8. The electrical assembly of claim 1, including a semiconductor package, wherein the off-assembly connections include pins, solder connections, leads, or wires.

9. The electrical assembly of claim 1,

wherein the traces and the off-assembly connections are on opposing sides of the electrical assembly; and

wherein an electrical connection between a trace and a respective off-assembly connection includes a plated through hole or conductive via.

10. The electrical assembly of claim 1,

wherein the off-assembly connections are organized as an array thereof; and wherein, for each of the traces one or more of the integrated transformer structures are defined therealong to induce respective of the compensating crosstalk signals and thereby oppose respective of the initial crosstalk signals introduced at a corresponding one of the offassembly connections by nearest neighbors thereof.

11. The electrical assembly of claim 10, wherein the array includes a linear array; wherein the nearest neighbors number two; and wherein, for essentially each of the trades, two of the integrated transformer structures are defined therealong to induce respective of the

compensating crosstalk signals and thereby oppose respective of the initial crosstalk signals introduced by the nearest neighbors.

he electrical assembly of claim 1,



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wherein the off-assembly	connections include on	ne of pins, s	solder joints,	leads,
and wires.				

- 13. The electrical assembly of claim 1, wherein the electrical assembly includes an integrated circuit chip.
- 14. The electrical assembly of claim 1, wherein the electrical assembly includes a chip carrier or package.
- 15. The electrical assembly of claim 1, wherein the electrical assembly includes a board or card.
- induced at a first off-assembly connection by one or more signals on one or more adjacent off-assembly connections, the crosstalk compensation circuit comprising: electrical traces respectively coupled to the first and adjacent connections; and the electrical traces traversing apertures defined in one or more voltage planes of the assembly to inductively couple compensating crosstalk signals having opposing polarity to the original crosstalk signal.

16. A crosstalk compensation circuit for offsetting an original crosstalk signal

- 17. The crosstalk compensation circuit of claim 16, wherein the assembly includes a semiconductor package; and wherein the first and adjacent connections are to a board or card.
- 18. The crosstalk compensation circuit of claim 16, wherein the assembly includes a semiconductor package; and wherein the first and adjacent connections are to an integrated circuit chip.
- 19. A method of making a circuit for canceling crosstalk introduced at a first electrical connection to a packaged integrated circuit by signals on an adjacent one or more electrical connections thereto, the method comprising:
 - defining a first signal trace from the first electrical connection and respective one or more second signal traces from the adjacent one or more electrical connections; and

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7	defining one or more transforther structures, the transformer structures
8	inductively coupling respective of the one or more second signal traces
9	to the first signal trace, the transformer structures matched to induce
10	signals substantially canceling the crosstalk introduced at the first
11	electrical connection.
1	20. A method as in claim 19,
2	wherein the first signal trace, the second signal traces and the transformer
3	structures are defined as part of the packaged integrated circuit.
1	21. A method as in claim 19,
2	wherein the first signal trace, the second signal traces and the transformer
3	structures are defined as part of a board or card to which the packaged
4	integrated circuit is connectable using the first and adjacent electrical
5	connections.
1	22. A method as in claim 19, wherein for each transformer structure, the
2	defining includes:
3	defining an aperture in a voltage plane of the integrated circuit chip; and
4	orienting the first signal trace and one of the second signal traces to define
5	substantially parallel portions thereof traversing at least a portion of the
6	aperture.

